

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): A mold apparatus for injection molding a disk substrate, comprising a cavity into which a molten resin is injected through a sprue bushing and a ~~recessed form~~ gate, and a signal transfer stamper disposed on ~~the a~~ fixed die side of said cavity, said mold apparatus comprising:

the sprue bushing disposed on the fixed side;

a gate cutter disposed on a movable die side wherein a projected portion for molding said recessed form gate provided at the a tip of said the sprue bushing, a recessed portion for molding said recessed form gate provided oppositely to said projected portion at the tip of a recessed form gate cutter disposed on the movable die side, and a center hole molding portion is provided at the an outer circumference of said sprue bushing and a recessed portion is formed at a tip of the gate cutter opposite to the projection portion of the sprue bushing and the gate cutter whose tip is recessed in shape is advanced from the movable die side to perform gate cutting.

Claim 2 (Canceled).

Claim 3 (Currently Amended): A mold apparatus for injection molding a disk substrate as set forth in claim 1, wherein said center hole molding portion comprises a straight molding portion for molding a straight portion with a hole diameter equal in direction with the axial direction on the side opposite to ~~the a~~ signal transfer surface side of said center hole of said disk substrate injection molded in said cavity, and a taper molding portion for molding a tapered portion with a hole diameter gradually enlarged toward the signal transfer

surface side between said straight portion of said center hole of said disk substrate injection molded in said cavity and said a signal transfer surface.

Claim 4 (Currently Amended): A mold apparatus for injection molding a disk substrate as set forth in claim 1, wherein the advance amount of ~~said recessed form~~ gate cutter is not less than the thickness of ~~said recessed form~~ gate and is not more than the ~~recessed form~~ gate thickness plus 0.5 mm.

Claim 5 (Currently Amended): A mold apparatus for injection molding a disk substrate as set forth in claim 3, wherein the position of cutting ~~said recessed form~~ gate by ~~said recessed form~~ gate cutter is set at a position equal to the hole diameter of said straight portion of said center hole.

Claim 6-10 (Canceled).